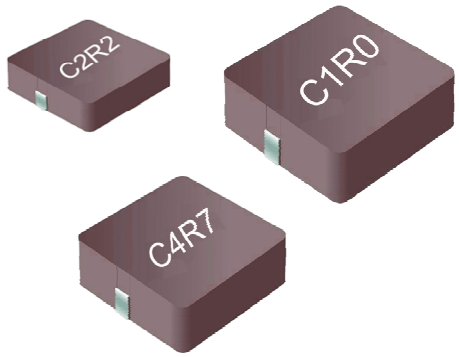
SMD Molding Power Inductor

◆ Features

1、Magnetically shielded construction, low DC resistance;
2、The use of magnetic iron powder ensure capability for large current;
3、Low audible core noise;
4、Ideal for DC-DC converter applications in hand held personal computer and etc;
5、Frequency Range: up to 3.0MHz;
6、RoHS compliant。



◆ Applications

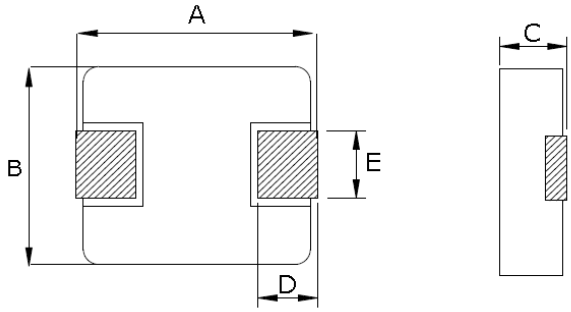
1、Smart phone、MID;
2、Next-generation mobile devices with multifunction such as adding color TV and digital movie cameras;
3、Flat-screen TVs, blue-ray disc recorders, set top box;
4、Notebooks, desktop computers, servers, graphic cards;
5、Portable gaming devices, personal navigation systems, personal multimedia devices;
6、Automotive systems;
7、Telecomm base stations。

◆ Lead Free Part Numbering

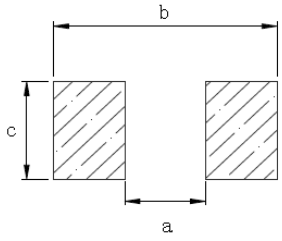
SLO	0610	H	100	M	T	T
(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) Series Type
(2) Dimension：A X C
(3) Material Code
(4) Inductance：2R2=2.2μH 100=10μH ;
(5) Inductance Tolerance：M=±20%, N=±30%
(6) Company Code
(7) Packaging：packed in embossed carrier tape

External Dimensions Unit(mm)



Recommended Land Pattern(mm)



◆ Dimensions

Series	A (mm)	B (mm)	C (mm)	D (mm)	E (mm)	a typ (mm)	b typ (mm)	c typ (mm)
SLO0610H	6.1±0.3	6.1±0.3	0.8 ±0.2	1.75±0.3	4.0±0.3	2.8	7.5	4.5

◆ Specification

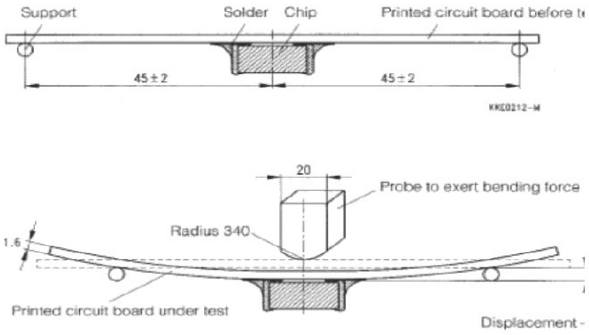
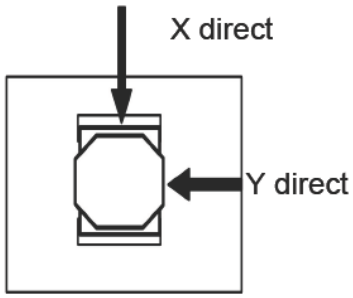
Part No.	Inductance	DC Resistance	Saturation Current		Heating Rating Current	
	L0 (μH)	DCR (mΩ)	Isat (A)		Irms (A)	
	±20 %, 100 kHz, 1V	MAX.	TYP.	MAX	TYP.	MAX
SLO0610H4R7MTT	4.7	172	2.8	2.5	2.2	2.0
SLO0610H6R8MTT	6.8	197	2.5	2.2	2.0	1.8
SLO0610H100MTT	10	310	2.1	1.9	1.6	1.4

Notes

1. All test data is referenced to 25 °C ambient
2. Operating temperature range - 55 °C to + 125 °C
3. Irms (A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)
4. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %
5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

◆ Reliability Test

Item	Specification and Requirement	Test Method
Solderability	1. No case deformation or change in apperarance 2. New solder coverage More than 90%	1.Preheat：155℃±5℃ ，60S±2S 2.Tin: lead-free. 3.Temperature:245℃±5℃，flux 3.0S±0.5S.
Mechanical shock	1. No case deformation or change in apperarance 2. △L/Lo≦±10%	1. Acceleration： 100G 2. Pulse time:：6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions
Mechanical vibration	1. No case deformation or change in apperarance 2. △L/Lo≦±10%	1. The test samples shall be soldered to the board. Then it shall be submitted to below test conditions. Fre. Range: 10~55Hz Total Amplitude: 1.5mm Sweeping Method: 10Hz to 55Hz to 10Hz Time: For 2 hours on each X,Y,Z axis. 2. Recovery: At least 2 hours of recovery under the standard condition after the test, followed by the measurement within 24 ±2 hours.
Thermal Shock	Inductance change: Within ± 10% Without distinct damage in appearance	1. First -55℃ for 30 minutes，last 125℃ for 30 minutes as 1 cycle. Go through 1000 cycles. 2. Max transfer time is 2 minutes. 3. Measured at room temperature after placing for 24±2 hours
Humidity Resistance	Inductance change: Within ± 10% Without distinct damage in appearance	1.Reflow 2 times, 2.85℃,85%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours
Low temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	1. Temperature：-55 ± 2℃ 2. Time：1000 hours 3. Measured at room temperature after placing for 24±2 hours
High temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	1. Temperature：+125 ± 2℃ 2. Time：1000 hours 3. Measured at room temperature after placing for 24±2 hours

Board Flex	Inductance change: Within ± 10% Without distinct damage in appearance	1、Run through IR reflow for 2 times； 2、Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down 3、The apparatus shall consist of mechanical means to apply a force which will bend the board (D) x = 2 mm minimum. 4、The duration of the applied forces shall be 60±5 sec. The force is to be applied only once to the oard. 
Terminal Strength	No removal or split of the termination or other defects shall occur.	1、The test samples shall be soldered to the board 2、Push the product vertically from the side of the sample using the thrust tester. 3、Automotive electronics：17.7N，60S±1s，X ，Ydirect. 

◆ Recommended Soldering Technologies

(1) Re-flowing Profile

Preheat condition: 150 ~200℃/60~180sec.

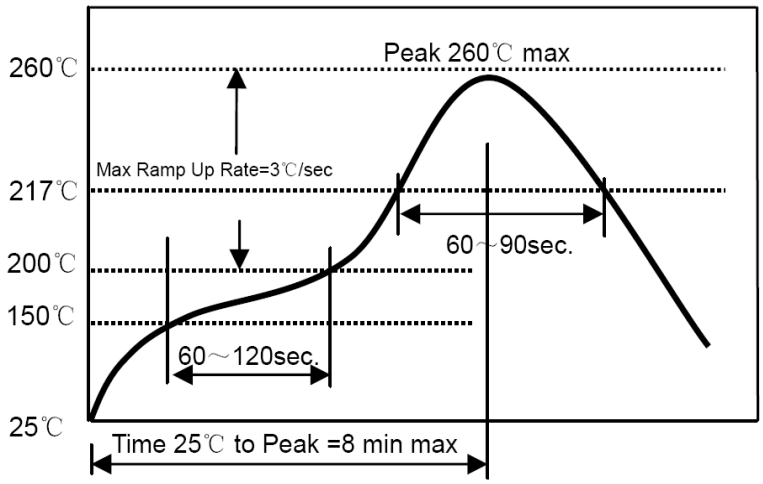
Allowed time above 217℃: 80~120sec.

Max temp: 260℃

Max time at max temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max



(2) Iron Soldering Profile

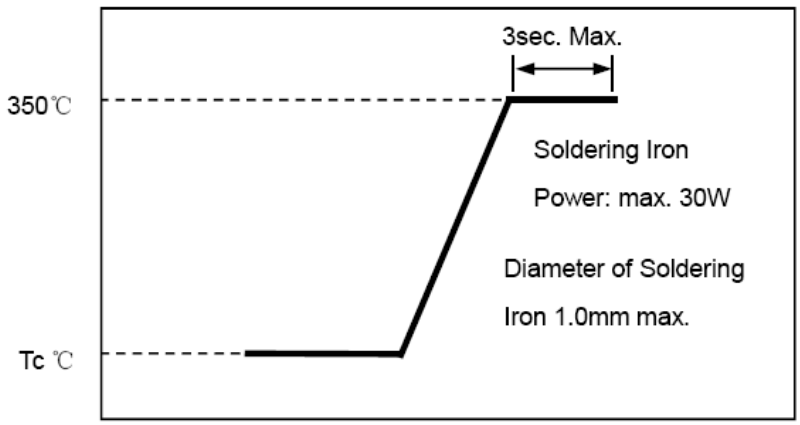
Iron soldering power: Max. 30W

Pre-heating: 150℃/60sec.

Soldering time: 3sec. Max.

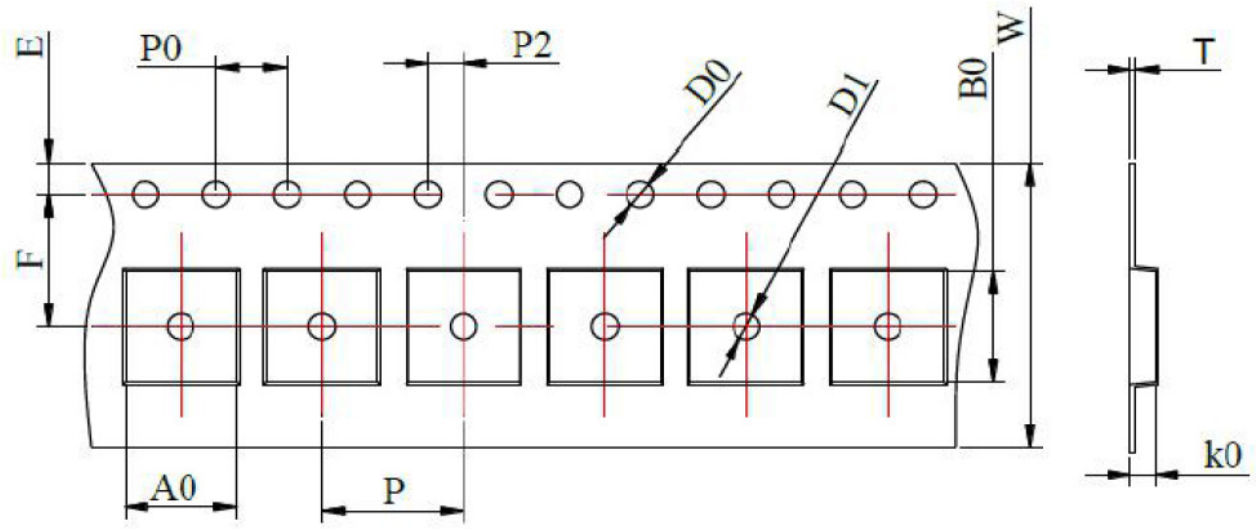
Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering



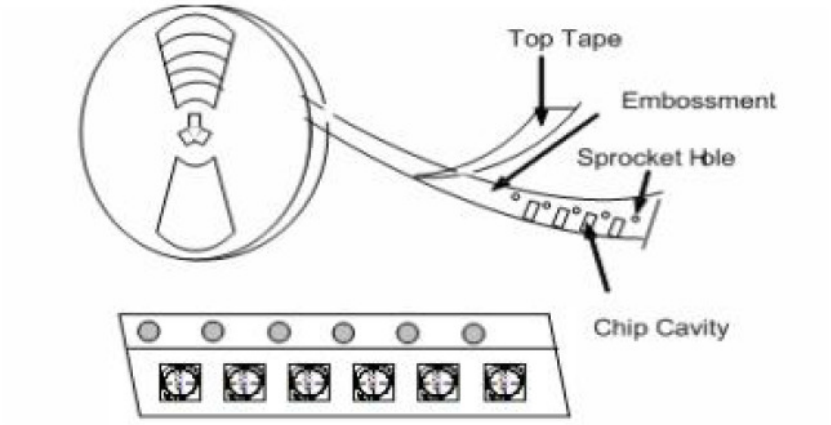
◆Packaging Information

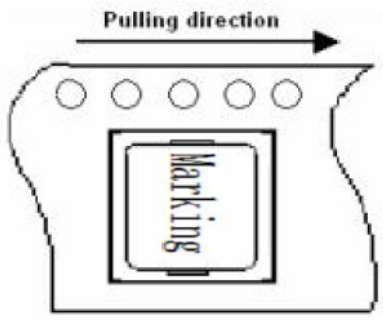
(1) Tape Packaging Dimensions（Unit：mm）



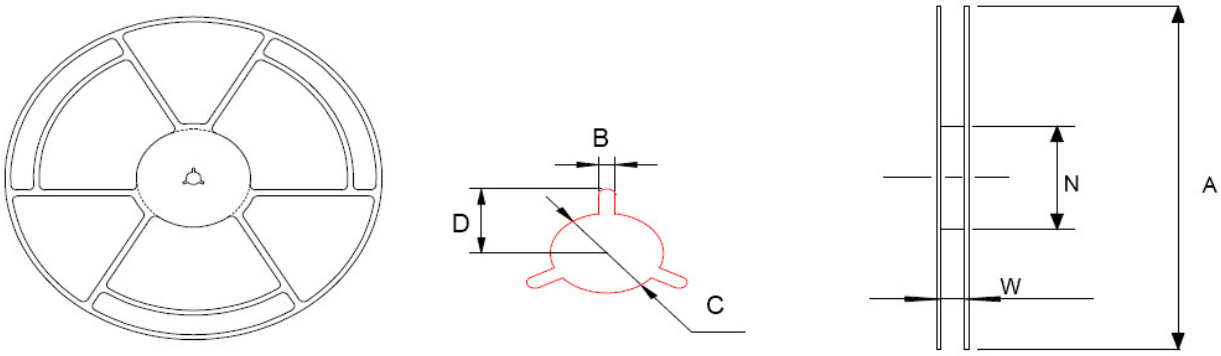
Type	Tape dimensions (mm)											
	W	P	P0	P2	D0	D1	T	A0	B0	K0	E	F
SLO0610H	16 ±0.3	12 ±0.1	4 ±0.1	2 ±0.1	1.5 ±0.1	1.5 ±0.1	0.35 ±0.05	6.9 ±0.1	7.5 ±0.1	2.1 ±0.1	1.75 ±0.1	7.5 ±0.1

Taping Drawings (UNIT:mm)





(2) Reel Dimensions（Unit：mm）



A	W	N	B	C	D
330+2.0	12.8±0.2	97±0.5	2.2+0.5	13.0±0.2	10.75±0.25

(3) Packaging Quantity(PCS)

Type	Standard Quantity		
	Reel	Inner box	Carton box
SLO0610H	**3000 pcs/reel**	**3Reel/box(9000pcs)**	**4 Middle boxes, (36,000pcs)**

(4) Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 N